



## Material Content Data Sheet



Halogen-Free

**Sales Product Name** TLF80511EJ V33

**Issued**

03. February 2022

**MA#** MA001207752

**Package** PG-DSO-8-52

**Weight\***

83.70 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.094	1.31	1.31	13072	13072
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		109	
	non noble metal	zinc	7440-66-6	0.036	0.04		435	
	non noble metal	iron	7439-89-6	0.728	0.87		8694	
	non noble metal	copper	7440-50-8	29.548	35.30	36.22	353025	362263
wire	non noble metal	copper	7440-50-8	0.038	0.05	0.05	460	460
encapsulation	organic material	carbon black	1333-86-4	0.101	0.12		1204	
	plastics	epoxy resin	-	4.637	5.54		55406	
	inorganic material	silicondioxide	60676-86-0	45.668	54.55	60.21	545627	602237
leadfinish	non noble metal	tin	7440-31-5	0.695	0.83	0.83	8305	8305
plating	noble metal	silver	7440-22-4	0.725	0.87	0.87	8656	8656
glue	plastics	epoxy resin	-	0.105	0.13		1252	
	noble metal	silver	7440-22-4	0.314	0.38	0.51	3755	5007
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

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